

# **Product Change Notification - LIAL-26WMMN354**

Date:

30 Nov 2018

**Product Category:** 

16-Bit - Microcontrollers and Digital Signal Controllers

**Affected CPNs:** 



### Notification subject:

CCB 3317 Cancellation Notice: For the qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package at ANAP assembly site.

**Notification text:** 

### **PCN Status:**

Cancellation notification

# PCN Type:

Manufacturing Change

## **Microchip Parts Affected:**

This change would have affected the selected products of the 200K wafer technology available in 28L SSOP package at ANAP assembly site

# **Description of Change:**

This qualification was originally performed to qualify palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package at ANAP assembly site.

### Impacts to Data Sheet:

Not applicable

## **Change Impact:**

Not applicable

#### **Reason for Change:**

Microchip has decided not to qualify qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package at ANAP assembly site

# **Change Implementation Status:**

Not applicable

# **Estimated First Ship Date:**

Not applicable

# Method to Identify Change:

Not applicable

### **Revision History:**

March 29, 2018: Issued initial notification.

November 30, 2018: Issued cancellation notice for the proposed qualification of of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L SSOP package at ANAP assembly site.

The change described in this PCN does not alter Microchip's current regulatory compliance



regarding the material content of the applicable products.

### Attachment(s):

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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#### Affected Catalog Part Numbers (CPN)

PIC24F08KA102-E/SS

PIC24F08KA102-I/SS

PIC24F08KA102T-E/SS

PIC24F08KL302-E/SS

PIC24F08KL302-I/SS

PIC24F08KL302T-I/SS

PIC24F08KL402-E/SS

PIC24F08KL402-I/SS

PIC24F08KL402T-I/SS

PIC24F16KA102-E/SS

PIC24F16KA102-I/SS

PIC24F16KA102T-I/SS

PIC24F16KA302-E/SS

PIC24F16KA302-I/SS

PIC24F16KA302T-I/SS

PIC24F16KL402-E/SS

PIC24F16KL402-I/SS

PIC24F16KL402T-I/SS

PIC24F32KA302-E/SS

PIC24F32KA302-I/SS

PIC24F32KA302T-I/SS

PIC24FV16KA302-E/SS

PIC24FV16KA302-I/SS

PIC24FV16KA302T-E/SS

PIC24FV16KA302T-I/SS

PIC24FV32KA302-E/SS

PIC24FV32KA302-I/SS

PIC24FV32KA302T-E/SS

PIC24FV32KA302T-I/SS

Date: Thursday, November 29, 2018